GRIND-X
OKAMOTO PRECISION SYSTEMS
Okamoto

Polishing

Semi-Auto CMP/ Polish System
Model SPP600S

Model SPP600S	
No. of Polish head	: 2
No. of Platen	: 1 (Ø610mm)
Platen drive Motor	: 3.7 Kw
Polish Mode	: 3 steps
Check drive Motor	: 0.4 Kw
Wafer size to Polish	: Max. 8”
Oscillation stroke	: Max. 100mm

Semi-Automatic Wafer CMP system for R & D

Okamoto Corporation

Semiconductor Equipment Division

3060 Scott Blvd.,

Santa Clara, CA 95054

TEL : (408) 654-8400 FAX: (408) 654-8405

www.okamoto-sed.com

FEATURES

Model SPP600S is designed to polish semiconductor materials such as silicon, carbide, ceramics, brittle materials and metal. Stable uniformity and edge shape is achieved by our unique polish head design, and temperature control system. Pad surface, pad bulk condition, and pad surface temperature detector system are available as options.

SPECIFICATIONS

Wafer size	Max. 8”
Process step	3-step
Polish table (Platen) Diameter Speed Type of Bearing Motor Material of table	1 platen Ø610 mm 10 - 100 rpm +/-3% Roller bearing (Air bearing is Option) 3.7 Kw AC SUS 420 (Alumina ceramics is Option)
Polish head (Carrier head) Coating Clamp system Release system Polish presser Chuck speed range Retainer ring material Vertical stroke Drive motor Oscillation stroke (speed)	2-axes Teflon Vacuum (0.75 Kw water sealed type) DI water and Air (or N2) Pneumatic (0 - 1.0 Kg/cm²) 1 - 100 rpm Alumina ceramic 200 mm 0.4 Kw AC Servo Max. 100mm (0.1 – 9.6 stroke/min)
Slurry supply system Velocity Tank capacity	Roller pump / Disposable 1 - 500 cc/min 20 liters
Removal rate	Poly-Si : 1300 Å/min Thermal Oxide : 2500 Å/min P-Teos : 3500 Å/min W : 500 Å/min Al : 400 Å/min Cu : 500 Å/min
Utility for electricity DI water consumption	3P, 200V, 8KVA 5 liter/min
Footprint (L x W x H)	35“x 30” x 74” (1380 x 1210 x 1873 mm)

Specifications subject to change without notice.